

WHAT IS CLAIMED IS:

1. A slurry for chemical mechanical polishing, which comprises a silica polishing material, an oxidizing agent, a benzotriazole-based compound, a diketone and  
5 water.
2. A slurry for chemical mechanical polishing according to Claim 1, wherein said diketone is at least one type of a compound selected from the group consisting  
10 of 1, 2-diketones, 1, 3-diketones and 1, 4-diketones.
3. A slurry for chemical mechanical polishing according to Claim 1, wherein a content ratio of said diketone to said benzotriazole-based compound (diketone /  
15 benzotriazole-based compound) is not less than 0.05 but not greater than 50.
4. A slurry for chemical mechanical polishing according to Claim 1, wherein a value of a pH is in a  
20 range of 1 to 7.
5. A slurry for chemical mechanical polishing according to Claim 1, wherein said silica polishing material is colloidal silica.